PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:

Todd O. Bolken

Serial No.: 10/791,192

Filed: March 2, 2004

For: TWO-STAGE TRANSFER MOLDING

DEVICE TO ENCAPSULATE MMC

MODULE

Confirmation No.: 1966

Examiner: D. Zarneke

Group Art Unit: 2891

Attorney Docket No.: 2269-4794.4US

(01-0185.04/US)

Notice of Allowance Mailed:

May 1, 2007

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FEE ADDRESSEE FOR RECEIPT OF PTO NOTICES RELATING TO MAINTENANCE FEES

Mail Stop ISSUE FEE Commissioner for Patents P.O. Box 1450 Alexandria, VA 22313-1450

Sir:

1. This letter is to specify that the FEE ADDRESSEE for this patent is:

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MICRON TECHNOLOGY, INC.

Mail Stop 525 8000 South Federal Way Boise, Idaho 83707-0006

- 2. The Customer Number for the Fee Addressee is 26809.
- 3. Any prior FEE ADDRESSEE for this patent is hereby revoked.
- 4. It is certified that the person whose signature appears below has the authority to change the FEE ADDRESSEE for this patent.

Respectfully submitted.

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JRD/djp:lmh
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